

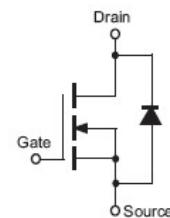
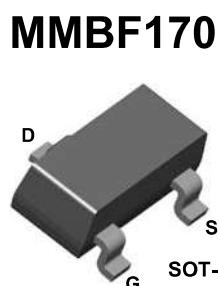
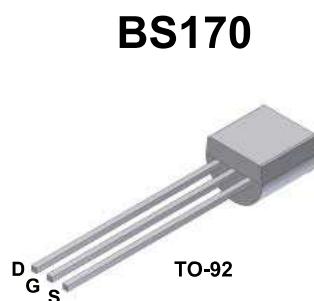
## BS170 / MMBF170 N-Channel Enhancement Mode Field Effect Transistor

### General Description

These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while providing rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 500mA DC. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

### Features

- High density cell design for low  $R_{DS(ON)}$ .
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.



### Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	BS170	MMBF170	Units
$V_{DSS}$	Drain-Source Voltage	60		V
$V_{DGR}$	Drain-Gate Voltage ( $R_{GS} \leq 1\text{M}\Omega$ )	60		V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$		V
$I_D$	Drain Current - Continuous	500	500	mA
	- Pulsed	1200	800	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to 150		°C
$T_L$	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300		°C

### Thermal Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	BS170	MMBF170	Units
$P_D$	Maximum Power Dissipation Derate above $25^\circ\text{C}$	830 6.6	300 2.4	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	150	417	°C/W

**Electrical Characteristics**  $T_A=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Type	Min.	Typ.	Max.	Units
<b>OFF CHARACTERISTICS</b>							
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$ , $I_D = 100\mu\text{A}$	All	60			V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 25\text{V}$ , $V_{\text{GS}} = 0\text{V}$	All			0.5	$\mu\text{A}$
$\text{I}_{\text{GSSF}}$	Gate - Body Leakage, Forward	$V_{\text{GS}} = 15\text{V}$ , $V_{\text{DS}} = 0\text{V}$	All			10	nA
<b>ON CHARACTERISTICS</b> (Notes 1)							
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 1\text{mA}$	All	0.8	2.1	3	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10\text{V}$ , $I_D = 200\text{mA}$	All		1.2	5	$\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}} = 10\text{V}$ , $I_D = 200\text{mA}$	BS170		320		mS
		$V_{\text{DS}} \geq 2 V_{\text{DS}(\text{on})}$ , $I_D = 200\text{mA}$	MMBF170		320		
<b>Dynamic Characteristics</b>							
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 10\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $f = 1.0\text{MHz}$	All		24	40	pF
$C_{\text{oss}}$	Output Capacitance		All		17	30	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		All		7	10	pF
<b>Switching Characteristics</b> (Notes 1)							
$t_{\text{on}}$	Turn-On Time	$V_{\text{DD}} = 25\text{V}$ , $I_D = 200\text{mA}$ , $V_{\text{GS}} = 10\text{V}$ , $R_{\text{GEN}} = 25\Omega$	BS170			10	ns
		$V_{\text{DD}} = 25\text{V}$ , $I_D = 500\text{mA}$ , $V_{\text{GS}} = 10\text{V}$ , $R_{\text{GEN}} = 50\Omega$	MMBF170			10	
$t_{\text{off}}$	Turn-Off Time	$V_{\text{DD}} = 25\text{V}$ , $I_D = 200\text{mA}$ , $V_{\text{GS}} = 10\text{V}$ , $R_{\text{GEN}} = 25\Omega$	BS170			10	ns
		$V_{\text{DD}} = 25\text{V}$ , $I_D = 500\text{mA}$ , $V_{\text{GS}} = 10\text{V}$ , $R_{\text{GEN}} = 50\Omega$	MMBF170			10	

**Note:**

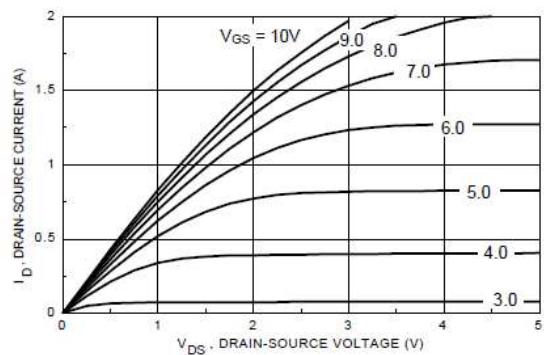
1. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

**Ordering Information**

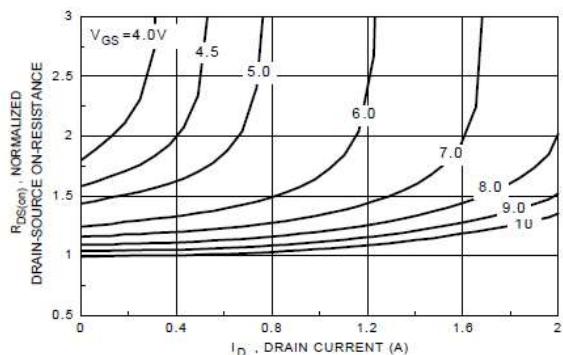
Part Number	Package	Package Type	Lead Frame	Pin array
BS170	TO-92	BULK	STRAIGHT	D G S
BS170_D26Z	TO-92	Tape and Reel	FORMING	D G S
BS170_D27Z	TO-92	Tape and Reel	FORMING	D G S
BS170_D74Z	TO-92	AMMO	FORMING	D G S
BS170_D75Z	TO-92	AMMO	FORMING	D G S
MMBF170	SOT-23	Tape and Reel		

## Typical Electrical Characteristics

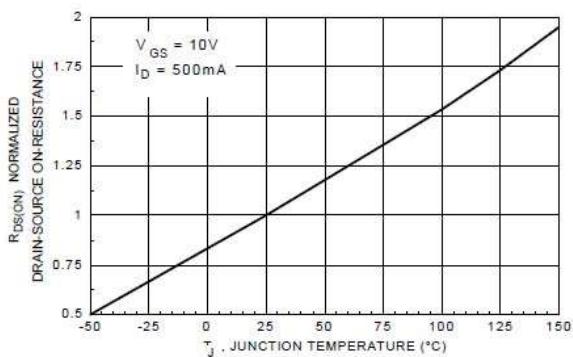
**BS170 / MMBF170**



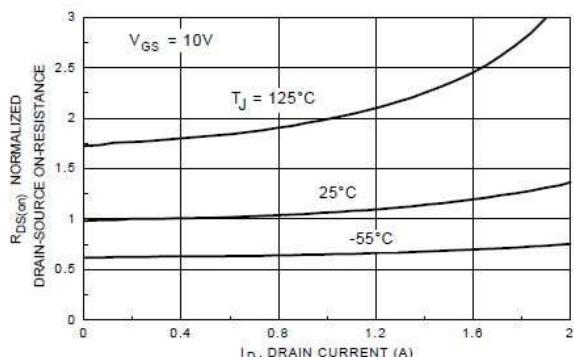
**Figure 1. On-Region Characteristics.**



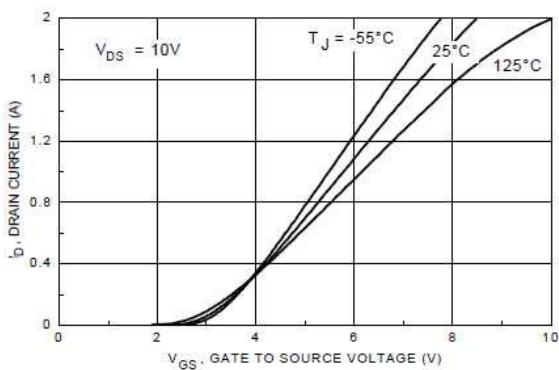
**Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.**



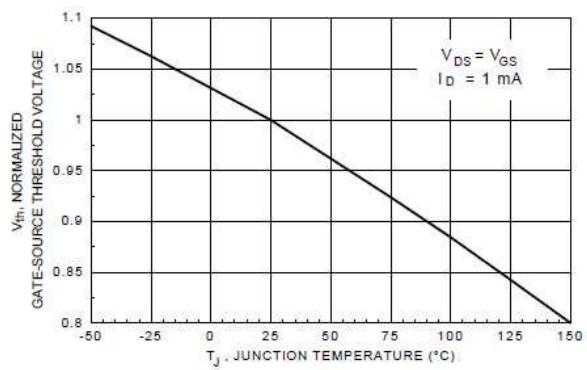
**Figure 3. On-Resistance Variation with Temperature.**



**Figure 4. On-Resistance Variation with Drain Current and Temperature.**



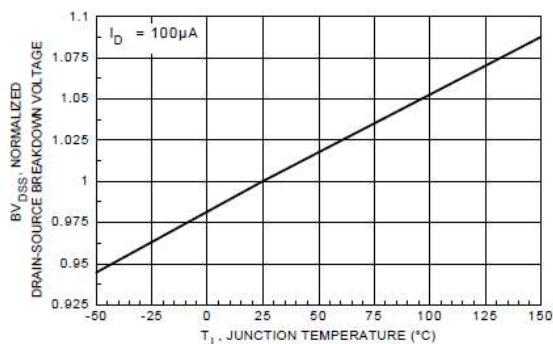
**Figure 5. Transfer Characteristics.**



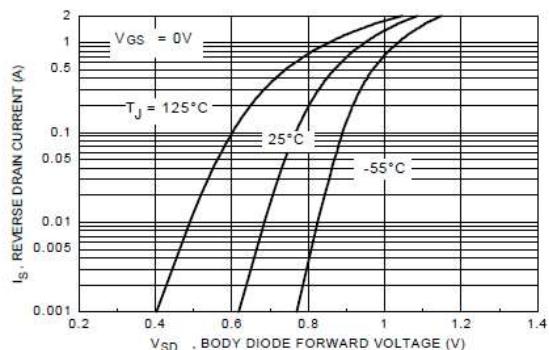
**Figure 6. Gate Threshold Variation with Temperature.**

## Typical Electrical Characteristics (continued)

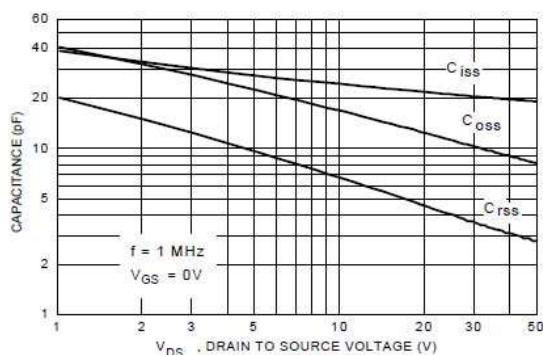
**BS170 / MMBF170**



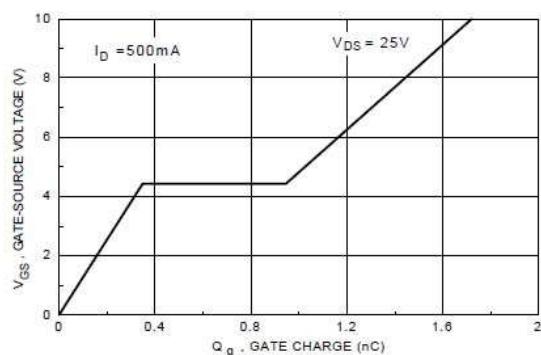
**Figure 7.** Breakdown Voltage Variation with Temperature.



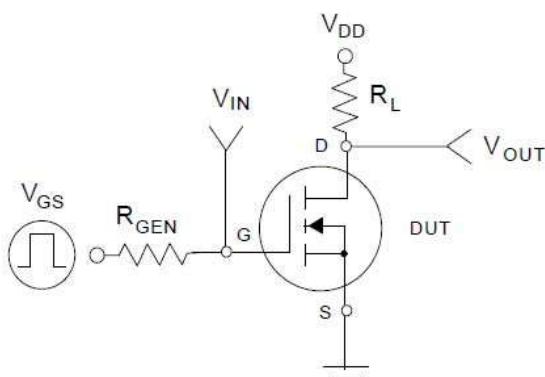
**Figure 8.** Body Diode Forward Voltage Variation with Current and Temperature.



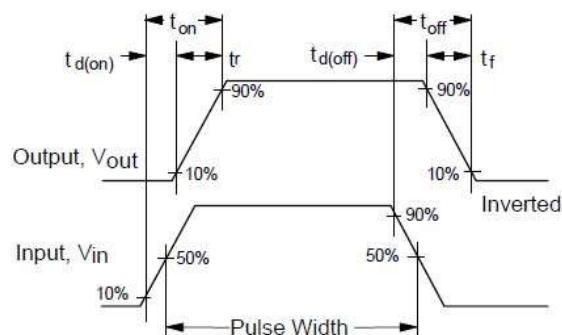
**Figure 9.** Capacitance Characteristics.



**Figure 10.** Gate Charge Characteristics.

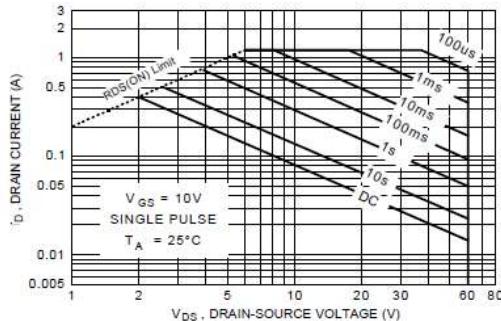


**Figure 11.** Switching Test Circuit.

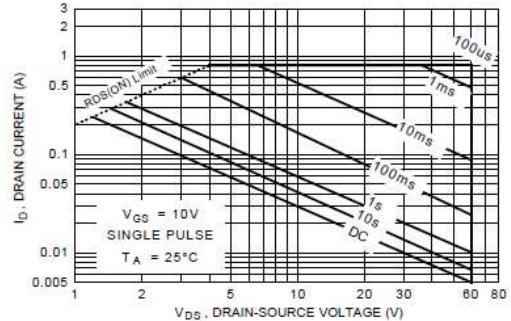


**Figure 12.** Switching Waveforms.

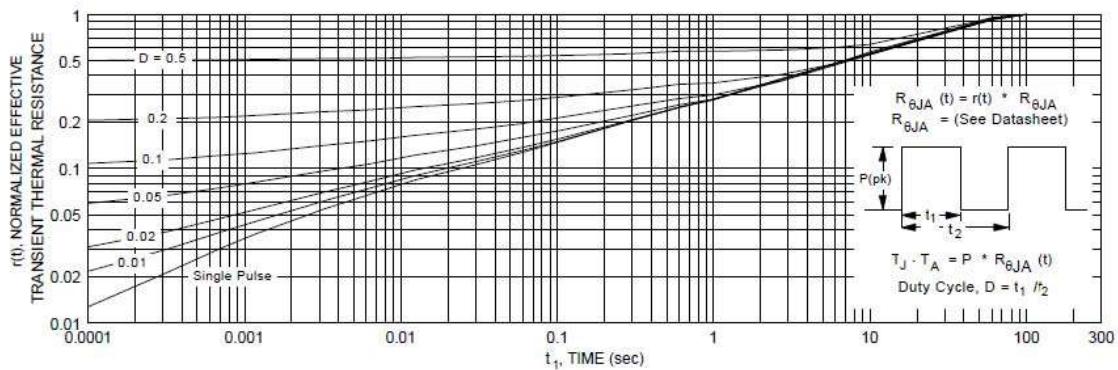
### Typical Electrical Characteristics (continued)



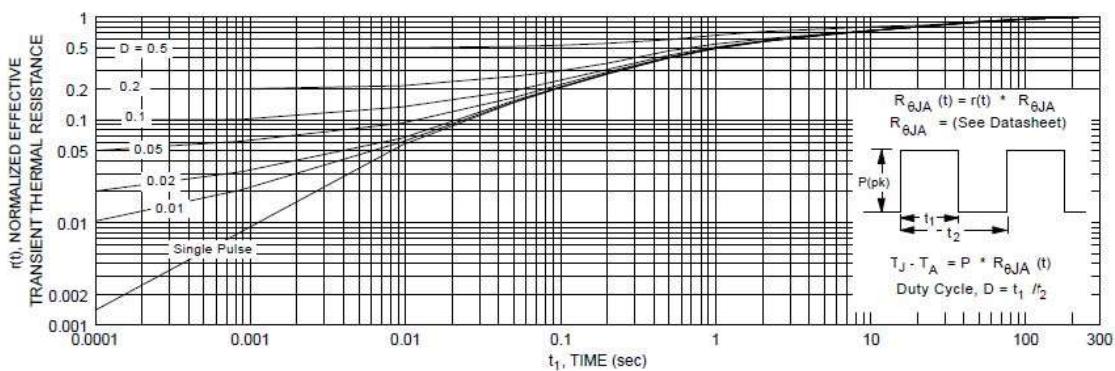
**Figure 13. BS170 Maximum Safe Operating Area.**



**Figure 14. MMBF170 Maximum Safe Operating Area.**



**Figure 15. TO-92, BS170 Transient Thermal Response Curve.**

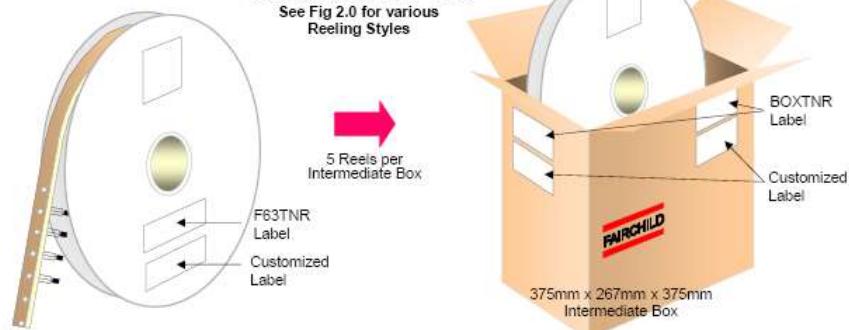


**Figure 16. SOT-23, MMBF170 Transient Thermal Response Curve.**

## TO-92 Tape and Reel Data

### TO-92 Packaging

Configuration: Figure 1.0



### TAPE and REEL OPTION

See Fig 2.0 for various Reeling Styles



### AMMO PACK OPTION

See Fig 3.0 for 2 Ammo Pack Options

BOXTNR Label sample



F63TNR Label sample

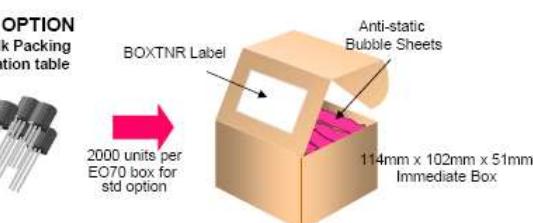
LOT: CBVK741B019	QTY: 3000
P/N: FDC633N	SPEC: 3000
FDC633N	REV: C
DC1: D964QAB	DC2: FN222N
FAIRCHILD SEMICONDUCTOR CORPORATION	(PSTNTR)

### BULK OPTION

See Bulk Packing Information table



BOXTNR Label  
2000 units per EO70 box for std option



## TO-92 Tape and Reel Data, continued

## TO-92 Packing

Information: Figure 2.0



TO-92 TNR/AMMO PACKING INFORMATION TABLE

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	B	2,000	D11Z
	C	2,000	D28Z
	D	2,000	D10Z
	E	2,000	D27Z
	F	2,000	D81Z
	G	2,000	D29Z
	H	2,000	D89Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm  
 Reel weight with components = 1.04 kg  
 Ammo weight with components = 1.02 kg  
 Max quantity per intermediate box = 10,000 units

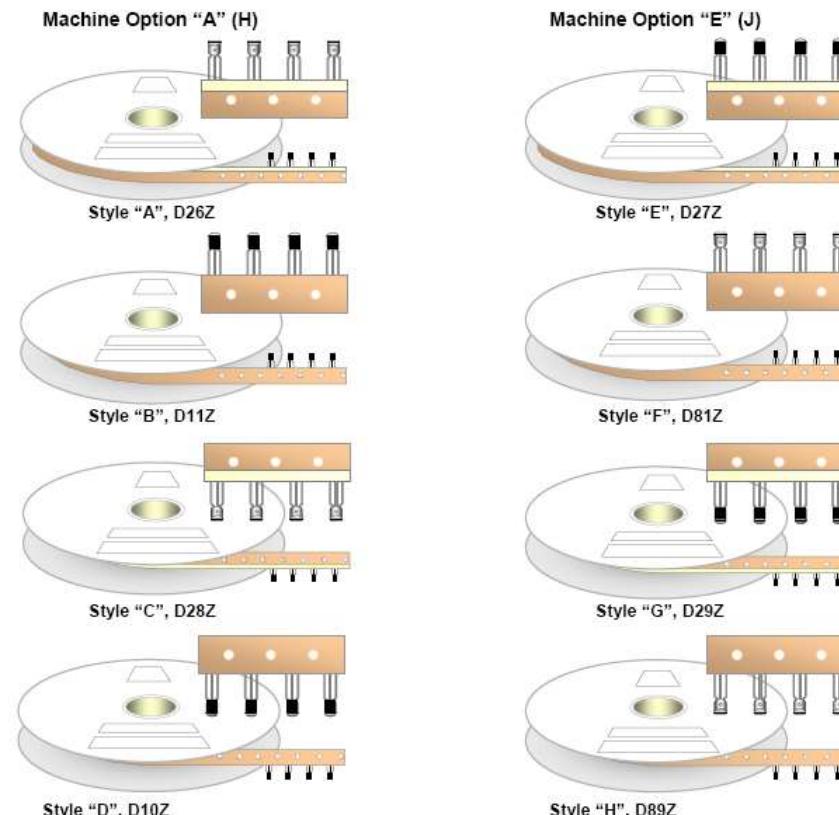
TO-92 BULK PACKING INFORMATION TABLE

EOL CODE / FLOW OPTION	DESCRIPTION	LEADCLIP DIMENSION	MINIMUM ORDER QTY	LEADFORM OUTLINE
NO EOL CODE	STRAIGHT LEADS	NO LEAD CLIP	2.0K / BOX	
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0K / BOX	
J35Z	TO-18 OPTION REVERSE	NO LEAD CLIP	2.0K / BOX	
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5K / BOX	
J60Z	TO-5 OPTION REVERSE	NO LEAD CLIP	1.5K / BOX	
J61Z	IN LINE 0.200 SPACING	NO LEAD CLIP	1.5K / BOX	

**TO-92 Tape and Reel Data, continued**

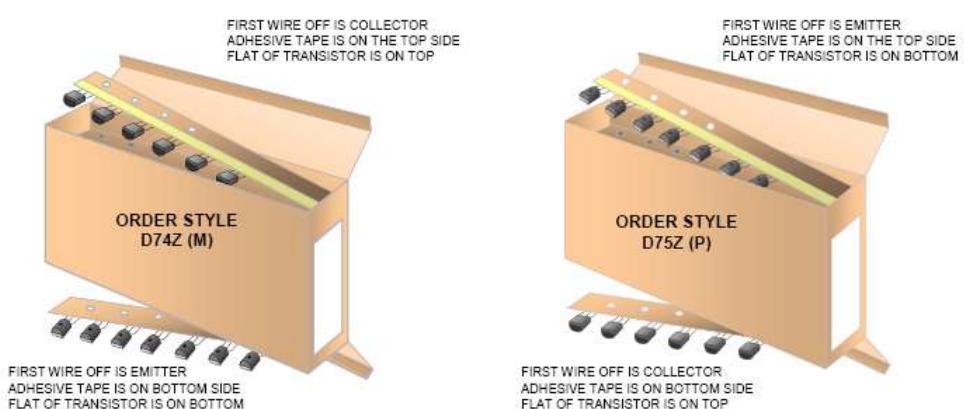
**TO-92 Reeling Style**

**Configuration:** Figure 3.0



**TO-92 Radial Ammo Packaging**

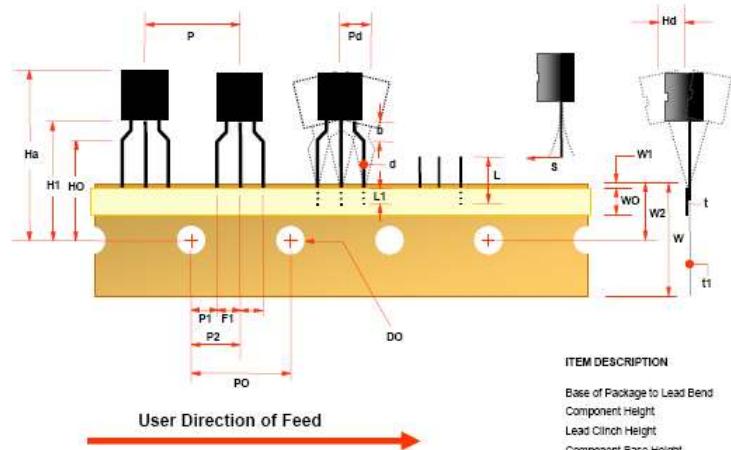
**Configuration:** Figure 4.0



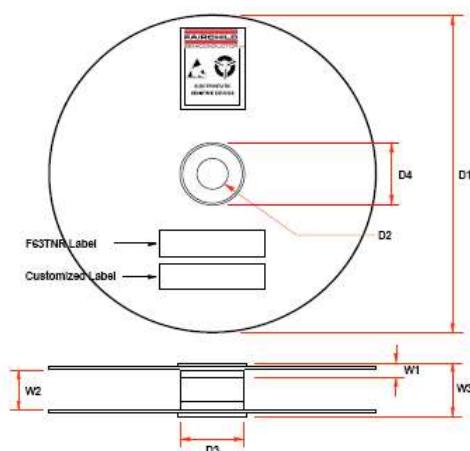
## TO-92 Tape and Reel Data, continued

### TO-92 Tape and Reel Taping

Dimension Configuration: Figure 5.0



### TO-92 Reel Configuration: Figure 6.0

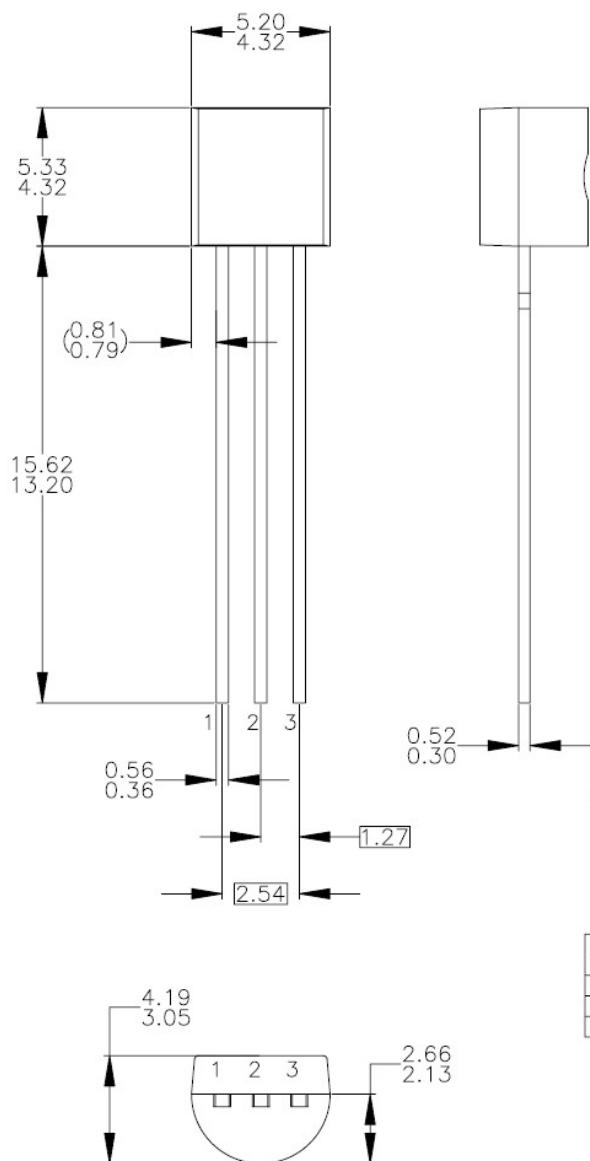


ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment ( side/side )	Pd	0.040 (max)
Component Alignment ( front/back )	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	P0	0.500 (+/- 0.020)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0.010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold-down Tape Width	WO	0.236 (+/- 0.012)
Hold-down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	s	0.004 (max)

Note: All dimensions are in inches.

ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard) (Small Hole)	D2	1.160	1.200
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches.

**Mechanical Dimensions ( TO-92 )****TO-92**

NOTES: UNLESS OTHERWISE SPECIFIED

- A) DRAWING WITH REFERENCE TO JEDEC TO-92 RECOMMENDATIONS.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M-1994.
- D) TO-92 (92,94,96,97,98) PIN CONFIGURATION:

Nd	92			94			96			97			98		
	P	F	M	P	F	M	P	F	M	P	F	M	P	F	M
1	E	S	S	E	S	S	B	D	G	C	G	D	C	G	D
2	B	D	G	C	G	D	E	S	S	B	D	G	E	S	S
3	C	G	D	B	D	G	C	G	D	E	S	S	B	D	G

LEGEND:  
 P — BIPOLAR      E — Emitter      D — Drain  
 F — JFET            B — Base          S — Source  
 M — DMOS           C — Collector     G — Gate

E) FOR PACKAGE 92, 94, 96, 97 AND 98:  
 PIN CONFIGURATION DRAIN "D" AND SOURCE "S"  
 ARE INTERCHANGEABLE AT JFET "F" OPTION.  
 F) DRAWING FILENAME: MKT-ZA03DREV3.

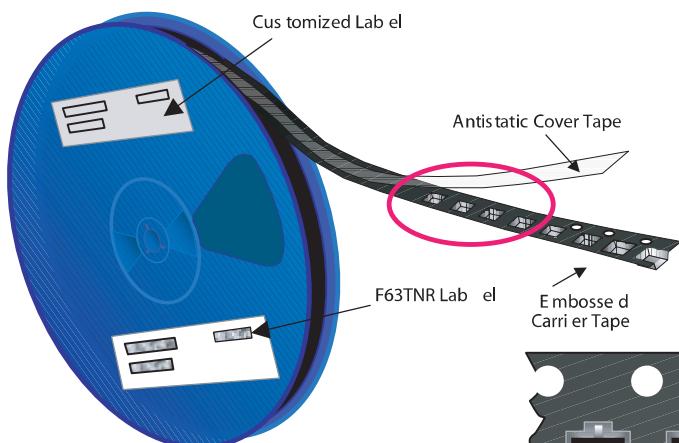
Dimensions in Millimeters

## SOT-23 Std Tape and Reel Data

**FAIRCHILD**  
SEMICONDUCTOR®

### SOT23-3L Packaging

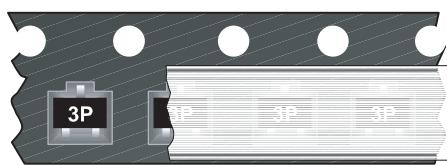
Configuration: Figure 1.0



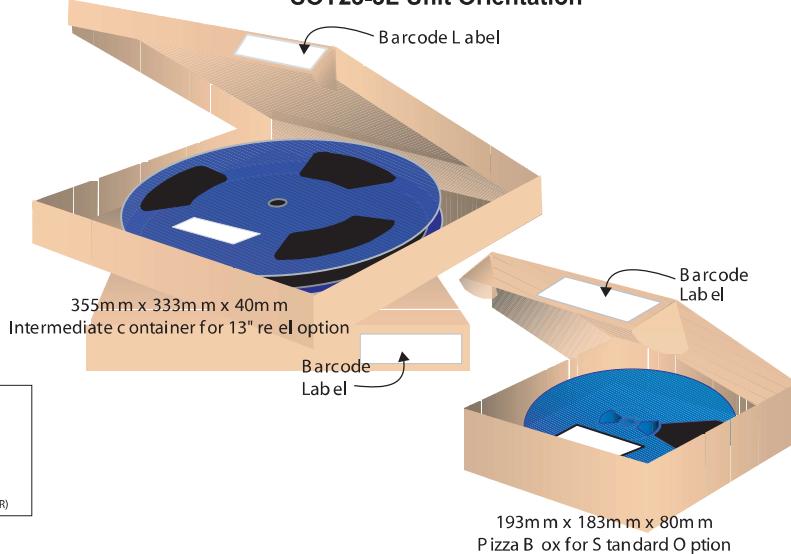
#### Packaging Description:

SOT23-3L parts are shipped in tape. The carrier tape is made from a dissipative (carbon-filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177mm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually labeled and placed inside a standard immediate box made of recyclable corrugated brown paper with a Fairchild logo printing. One box contains five reels maximum. And these immediate boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped.



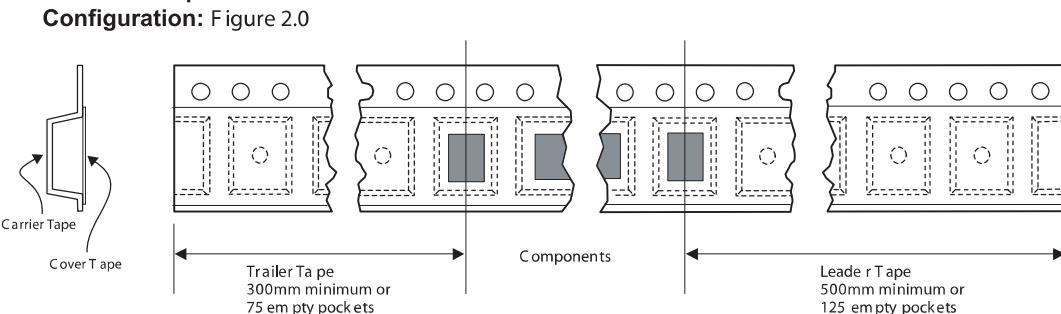
### SOT23-3L Unit Orientation



#### Barcode Label sample



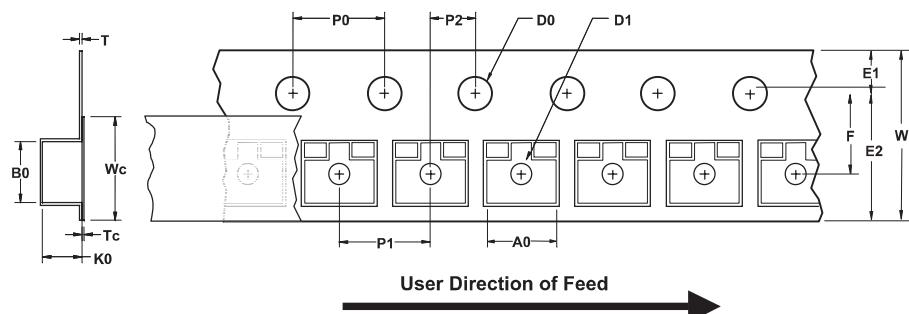
### SOT23-3L Tape Leader and Trailer Configuration: Figure 2.0



## SOT-23 Std Tape and Reel Data, continued

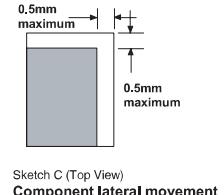
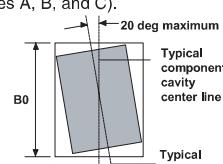
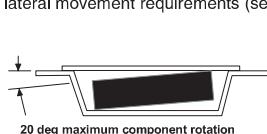
### SOT23-3L Embossed Carrier Tape

Configuration: Figure 3.0

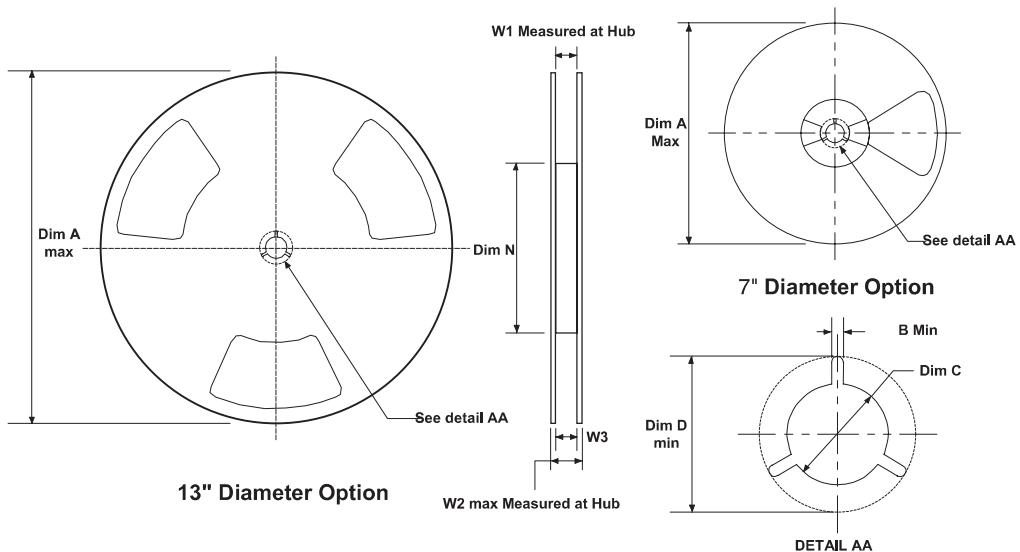


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
<b>SOT-23 (8mm)</b>	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



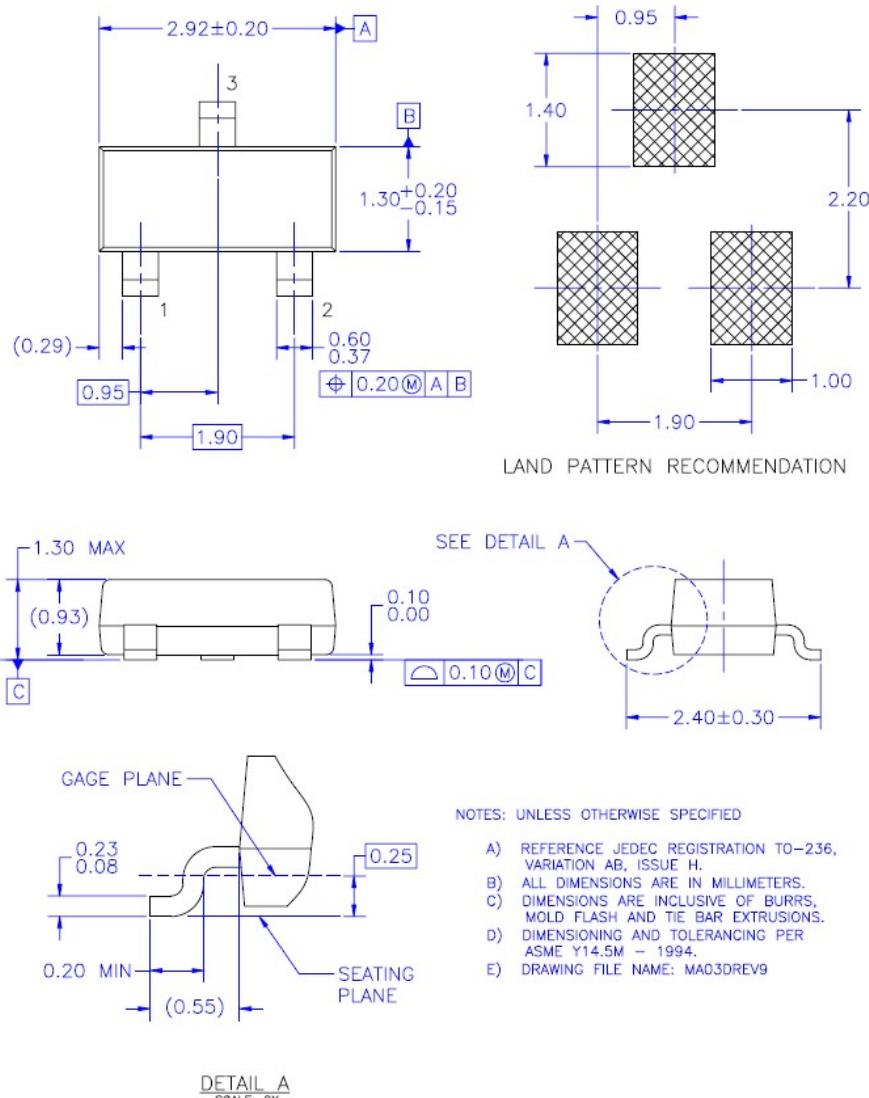
### SOT23-3L Reel Configuration: Figure 4.0



Dimensions are in inches and millimeters								
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4
								Dim W3 (LSL-USL)
								0.311 - 0.429 7.9 - 10.9

## Mechanical Dimensions ( SOT-23 )

### SOT-23



Dimensions in Millimeters



## TRADEMARKS

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AccuPower™	FRFET®	PowerTrench®	The Power Franchise®
Auto-SPM™	Global Power Resource <sup>SM</sup>	PowerXS™	the power franchise
Build it Now™	Green FPST™	Programmable Active Droop™	TinyBoost™
CorePLUS™	Green FPST™ e-Series™	QFET®	TinyBuck™
CorePOWER™	Gmax™	QS™	TinyCalc™
CROSSVOLT™	GTO™	Quiet Series™	TinyLogic®
CTL™	IntelliMAX™	RapidConfigure™	TINYOPTO™
Current Transfer Logic™	ISOPLANAR™	Saving our world, 1mW/W/kW at a time™	TinyPower™
DEUXPEED®	MegaBuck™	SignalWise™	TinyPWM™
Dual Cool™	MICROCOUPLER™	SmartMax™	TinyWire™
EcoSPARK®	MicroFET™	SMART START™	TriFault Detect™
EfficientMax™	MicroPak™	SPM®	TRUECURRENT™*
<b>F</b> ®	MicroPak2™	STEALTH™	µSerDes™
Fairchild®	MillerDrive™	SuperFET™	
Fairchild Semiconductor®	MotionMax™	SuperSOT™-3	UHC®
FACT Quiet Series™	Motion-SPM™	SuperSOT™-6	Ultra FRFET™
FACT®	OptoHiT™	SuperSOT™-8	UniFET™
FAST®	OPTOLOGIC®	SupreMOS™	VCXTM
FastvCore™	OPTOPLANAR®	SyncFET™	VisualMax™
FETBench™		Sync-Lock™	XS™
FlashWriter®*	PDP SPM™		
FPS™	Power-SPM™		
F-PFS™			

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## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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